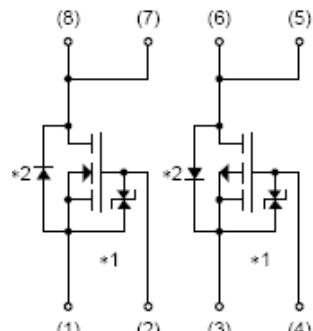


## Switching

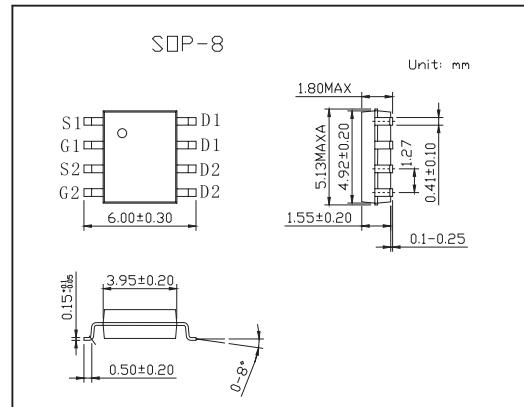
### KP8M9

#### ■ Features

- Low on-resistance.
- Built-in G-S Protection Diode.
- Small and Surface Mount Package.
- Power switching, DC / DC converter.



\*1 ESD PROTECTION DIODE  
\*2 BODY DIODE



#### ■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-source voltage	V <sub>DSS</sub>	30	-30	V
Gate-source voltage	V <sub>GSS</sub>	20	-20	V
Drain current Continuous	I <sub>D</sub>	±9.0	±5.0	A
Drain current Pulsed *	I <sub>DP</sub>	±36	±20	A
Source current (Body diode) Continuous	I <sub>S</sub>	1.6	-1.6	A
Source current (Body diode) Pulsed *	I <sub>SP</sub>	36	-20	A
Total power dissipation	P <sub>D</sub>	2		W
Channel temperature	T <sub>ch</sub>		150	°C
Storage temperature	T <sub>stg</sub>		-55 to +150	°C
Channel to ambient	R <sub>th</sub> (ch-a)		62.5	°C/W

\* Pw≤10 μ s, Duty cycle≤1%

## KP8M9

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons		Min	Typ	Max	Unit
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> =20V, V <sub>DSD</sub> =0V	N-Ch			10	μ A
		V <sub>GS</sub> =-20V, V <sub>DSD</sub> =0V	P-Ch			±10	
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V	N-Ch	30			V
		I <sub>D</sub> =-1mA, V <sub>GS</sub> =0V	P-Ch	-30			
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	N-Ch			1	μ A
		V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	P-Ch			-1	
Gate threshold voltage	V <sub>GS (th)</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =1mA	N-Ch	1.0		2.5	V
		V <sub>DS</sub> =-10V, I <sub>D</sub> =-1mA	P-Ch	-1.0		-2.5	
Static drain-source on-state resistance	R <sub>DSD (on)</sub>	I <sub>D</sub> =9.0A, V <sub>GS</sub> =10A	N-Ch		12	18	m Ω
		I <sub>D</sub> =9.0A, V <sub>GS</sub> =4.5V			16	24	
		I <sub>D</sub> =9.0A, V <sub>GS</sub> =4V			17	25	
Static drain-source on-state resistance	R <sub>DSD (on)</sub>	I <sub>D</sub> =-5.0A, V <sub>GS</sub> =-10A	P-Ch		30	42	m Ω
		I <sub>D</sub> =-2.5A, V <sub>GS</sub> =-4.5V			40	56	
		I <sub>D</sub> =-2.5A, V <sub>GS</sub> =-4.0V			45	63	
Forward transfer admittance	Y <sub>fs</sub>	I <sub>D</sub> =9.0A, V <sub>DSD</sub> =10V	N-Ch	7.0			S
		I <sub>D</sub> =-2.5A, V <sub>DSD</sub> =-10V	P-Ch	4.5			
Input capacitance	C <sub>iss</sub>	N-Channel V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, f=1MHz	N-Ch		1190		pF
			P-Ch		1400		
Output capacitance	C <sub>oss</sub>	P-Channel V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz	N-Ch		340		pF
			P-Ch		300		
Reverse transfer capacitance	C <sub>rss</sub>	N-Ch V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V, f=1MHz	N-Ch		190		pF
			P-Ch		230		
Turn-on delay time	t <sub>d (on)</sub>	I <sub>D</sub> =4.5A, V <sub>DD</sub> =15V	N-Ch		10		ns
		I <sub>D</sub> =-2.5A, V <sub>DD</sub> =-15V	P-Ch		15		
Rise time	tr	N-Channel V <sub>GS</sub> =10V, R <sub>L</sub> =3.33 Ω , R <sub>G</sub> =10 Ω	N-Ch		15		ns
			P-Ch		30		
Turn-off delay time	t <sub>d (off)</sub>	P-Channel V <sub>GS</sub> =-10V, R <sub>L</sub> =6.0 Ω , R <sub>G</sub> =10 Ω	N-Ch		55		ns
			P-Ch		80		
Fall time	t <sub>f</sub>	N-Ch V <sub>GS</sub> =-10V, R <sub>L</sub> =6.0 Ω , R <sub>G</sub> =10 Ω	N-Ch		22		ns
			P-Ch		40		
Total gate charge	Q <sub>g</sub>	N-Channel V <sub>DD</sub> =15V, V <sub>GS</sub> =5V, I <sub>D</sub> =9.0A	N-Ch		15	21	nC
			P-Ch		16		
Gate-source charge	Q <sub>gs</sub>	P-Channel V <sub>DD</sub> =-15V, V <sub>GS</sub> =-5V, I <sub>D</sub> =-5.0A	N-Ch		3.0		nC
			P-Ch		3.5		
Gate-drain charge	Q <sub>gd</sub>	N-Ch V <sub>DD</sub> =-15V, V <sub>GS</sub> =-5V, I <sub>D</sub> =-5.0A	N-Ch		6.1		nC
			P-Ch		6.5		
Forward voltage	V <sub>SD</sub>	I <sub>S</sub> =6.4A, V <sub>GS</sub> =0V	N-Ch			1.2	V
		I <sub>S</sub> =-1.6A, V <sub>GS</sub> =0V	P-Ch			-1.2	